



### Features

- » Thermal Conductivity: 0.8 W/mK
- » High performance, thermally conductive acrylic adhesive.
- » High bond strength to a variety of surfaces Double sided pressure sensitive adhesive tape.

### Application

- » Fixed the radiator to the encapsulated chip
- » Fixed the radiator to the power supply circuit or vehicle control circuit board
- » Can replace hot melt glue, screw, fastener, etc.fixed mode

### Product Specification

#### Product Thicknesses

- TIA605:0.005"(0.127mm)
- TIA606:0.006"(0.152mm)
- TIA608:0.008"(0.203mm)
- TIA610:0.010"(0.254mm)
- TIA612:0.012"(0.304mm)
- TIA615:0.015"(0.381mm)
- TIA620:0.020"(0.508mm)

#### Product Sizes

40" x 100'(106mm x 30.48M)

Individual die cut shapes can be supplied. Please contact us for confirming.

TIA™600 series rolls type can add with fiberglass film reinforced.

**TIA™ 600FG Series** are mostly used for bonding heat dissipation fins, microprocessors and other power consumption semiconductors. This type of adhesive tape possesses ultimate bonding strength with low thermal impedance, with which in effect can be able to replace the method of lubricating grease and mechanical fixing.

Typical Properties of TIA™ 600FG Series		
Color	White	Visual
Adhesive Type	Acrylic Adhesive	*****
Backing Type	Fiberglass	*****
Operating Temp	-45°C-120°C	*****
Thickness range	0.0050"-0.010"	ASTM D374
Dielectric Breakdown Voltage	>1000 VAC	ASTM D149
Thermal Conductivity	0.8 W/mK	ASTM D5470
180° Peel Adhesion	> 800 g/inch (Steel, Immediate)	PSTC-1
180° Peel Adhesion	> 800 g/inch (Steel after 24 hrs)	PSTC-1
Holding Power 25 ° C/Hours	> 48 Hours	PSTC-7
Holding Power 80 ° C/Hours	> 48 Hours	PSTC-7
Flame Rating	94 V0	UL E331100

Thermally Conductive Materials

Heat Generating Materials

Thermally Conductive Plastics

Foaming Silica Gel

Die-Cutting Products

#### Canada:

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Thermal Conductive Interface Materials  
Application Technology Download



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